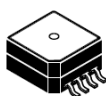


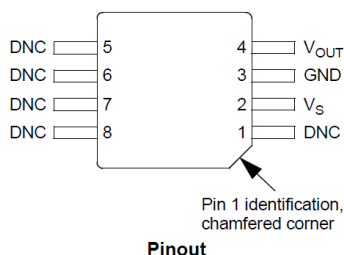
20 to 115 kPa, absolute, integrated pressure sensor

Super small outline package



MPXHZ6116A6U/6T1
Case 98ARH99066A

Top view



Features

- Resistant to high humidity and common automotive media
- 1.5% maximum error over 0 °C to 85 °C
- Temperature compensated from -40 °C to +125 °C
- Durable thermoplastic (PPS) surface mount package (SSOP)
- Ideally suited for microprocessor or microcontroller-based systems

Description

The MPXHZ6116A series pressure sensor integrates on-chip, bipolar op amp circuitry and thin film resistor networks to provide a high output signal and temperature compensation. The sensor's packaging has been designed to provide resistance to high humidity conditions as well as common automotive media. The small form factor and high reliability of on-chip integration make this sensor a logical and economical choice for the system designer.

The MPXHZ6116A series pressure sensor is a state-of-the-art, monolithic, signal conditioned sensor designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This piezoresistive transducer combines advanced micromachining techniques, thinfilm metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure.



1 Ordering information

Table 1. Ordering information

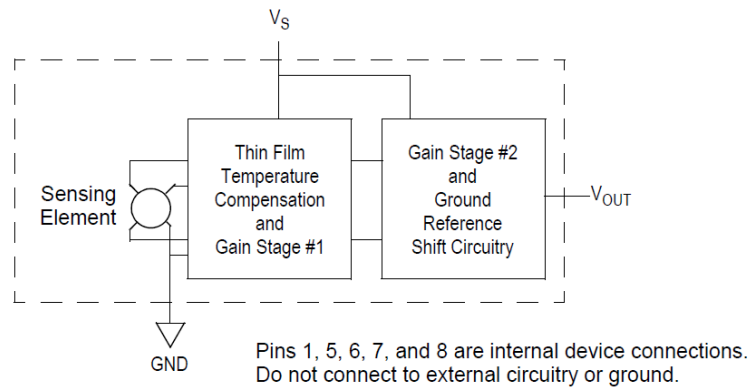
Part number	Shipping	Package	# of Ports				Pressure type		Device marking
			None	Single	Dual	Gauge	Differential	Absolute	
Small Outline Package (MPXHZ6116A series)									
MPXHZ6116A6U	Rail	98ARH99066A	•					•	MPHZ6116A
MPXHZ6116A6T1	Tape and Reel	98ARH99066A	•					•	MPHZ6116A

2 General description

2.1 Block diagram

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

Figure 1. Fully integrated pressure sensor schematic



2.2 Pinout

Figure 2. Device pinout (top view)

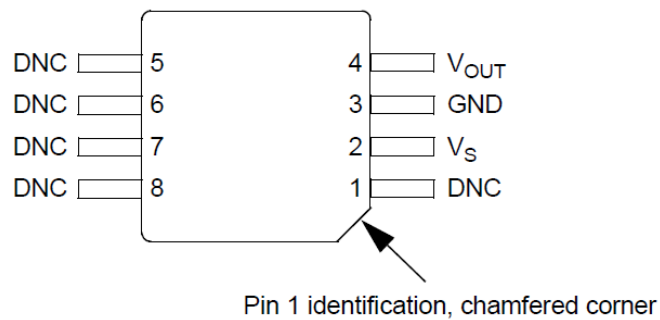


Table 2. Pin functions

Pin	Name	Function
1	DNC	Do not connect to external circuitry or ground. Pin 1 is denoted by chamfered corner.
2	V_S	Voltage supply
3	GND	Ground
4	V_{OUT}	Output voltage
5	DNC	Do not connect to external circuitry or ground.
6	DNC	Do not connect to external circuitry or ground.
7	DNC	Do not connect to external circuitry or ground.
8	DNC	Do not connect to external circuitry or ground.

3 Mechanical and electrical specifications

3.1 Maximum ratings

Table 3. Maximum ratings ⁽¹⁾

Rating	Symbol	Value	Units
Maximum pressure	P_{max}	400	kPa
Storage temperature	T_{stg}	-40 to +125	°C
Operating temperature	T_A	-40 to +125	°C
Output source current @ full-scale output ⁽²⁾	I_{o+}	+0.5	mAdc
Output sink current @ minimum pressure offset ⁽²⁾	I_{o-}	-0.5	mAdc

1.Exposure beyond the specified limits may cause permanent damage or degradation to the device.

2.Maximum output current is controlled by effective impedance from V_{OUT} to GND or V_{OUT} to V_S in the application circuit.

3.2 Operating characteristics

Table 4. Operating characteristics ($V_S = 5.0$ Vdc, $T_A = 25$ °C unless otherwise noted, decoupling circuit shown in Figure 4 required to meet electrical specifications.)

Characteristic		Symbol	Min	Typ	Max	Unit
Pressure range		P_{OP}	20	—	115	kPa
Supply voltage ⁽¹⁾		V_S	4.75	5.0	5.25	Vdc
Supply current		I_S	—	6.0	10	mAdc
Full-scale span ⁽²⁾	(0 °C to 85 °C)	V_{FSS}	—	4.2	—	Vdc
Offset ⁽³⁾	(0 °C to 85 °C)	V_{off}	0.335	0.399	0.463	Vdc
Sensitivity		V/P	—	44.2	—	mV/kPa
Accuracy ⁽⁴⁾	(0 °C to 85 °C)	—	-1.5	—	+1.5	% V_{FSS}
Pressure range		P_{OP}	20	—	115	kPa

1.Device is ratiometric within this specified excitation range.

2.Full-scale span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.

3.Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.

4.Accuracy (error budget) is the deviation in actual output from nominal output over the entire pressure range and temperature range as a percent of V_{SS} span at 25 °C due to all sources of error including the following:

Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.

Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.

Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from minimum or maximum rated pressure at 25 °C.

Offset Stability: Output deviation, after 1000 temperature cycles, -40 °C to 125 °C, and 1.5 million pressure cycles, with minimum rated pressure applied.



TcSpan: Output deviation over the temperature range of 0 °C to 85 °C, relative to 25 °C.

TcOffset: Output deviation with minimum pressure applied, over the temperature range of 0 °C to 85 °C, relative to 25 °C.

4 On-chip temperature compensation and calibration

The performance over temperature is achieved by integrating the shear-stress strain gauge, temperature compensation, calibration, and signal conditioning circuitry onto a single monolithic chip.

Figure 3 illustrates the configuration in the basic chip carrier (case 98ARH99066A) prior to porting. A gel die coat isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm. The gel die coat and durable thermoplastic package provide a media resistant barrier that allows the sensor to operate reliably in high humidity conditions as well as common automotive media.

NOTE

The MPXHZ6116A pressure sensor operating characteristics, internal reliability and qualification tests are based on use of air as the pressure media. Media, other than air, may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your applic

Figure 4 shows the recommended decoupling circuit for interfacing the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

Figure 3. Cross-sectional diagram SSOP (not to scale)

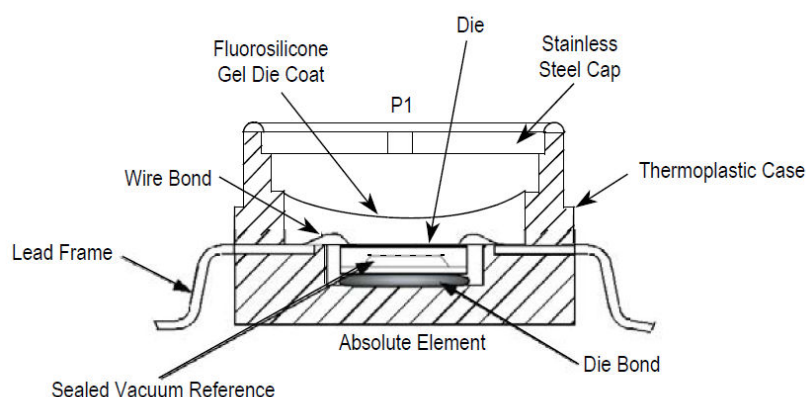


Figure 4. Recommended power supply decoupling and output filtering

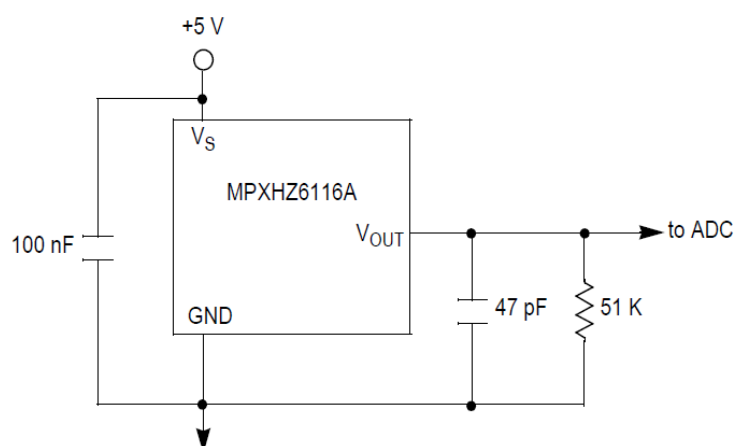
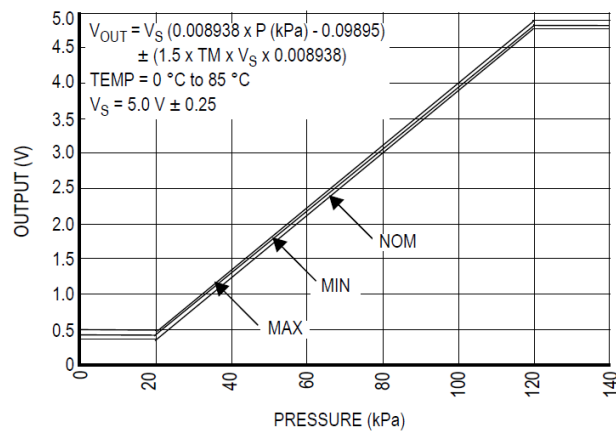
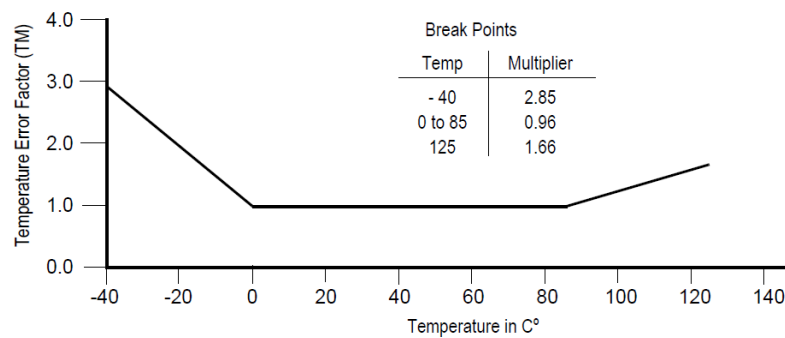
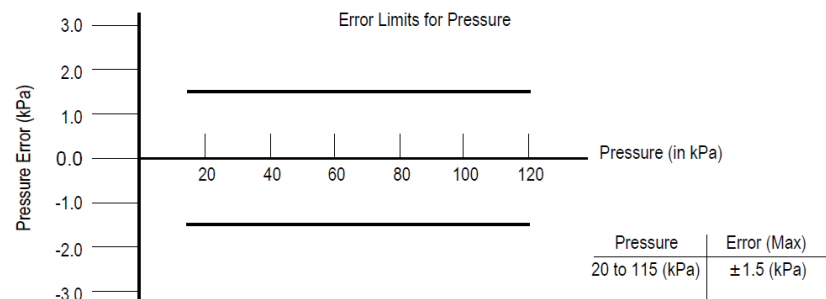


Figure 5. Output vs. absolute pressure

Figure 6. Temperature error band


NOTE: The Temperature Multiplier is a linear response from 0°C to -40°C and from 85°C to 125°C

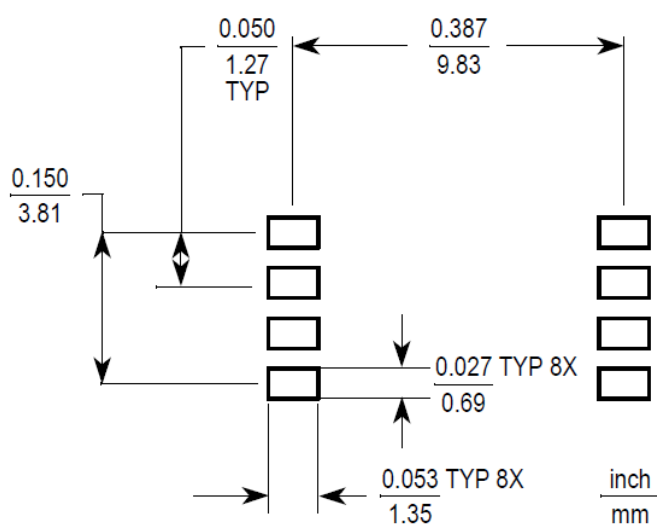
Figure 7. Pressure error band


5 Package information

5.1 Minimum recommended footprint for super small packages

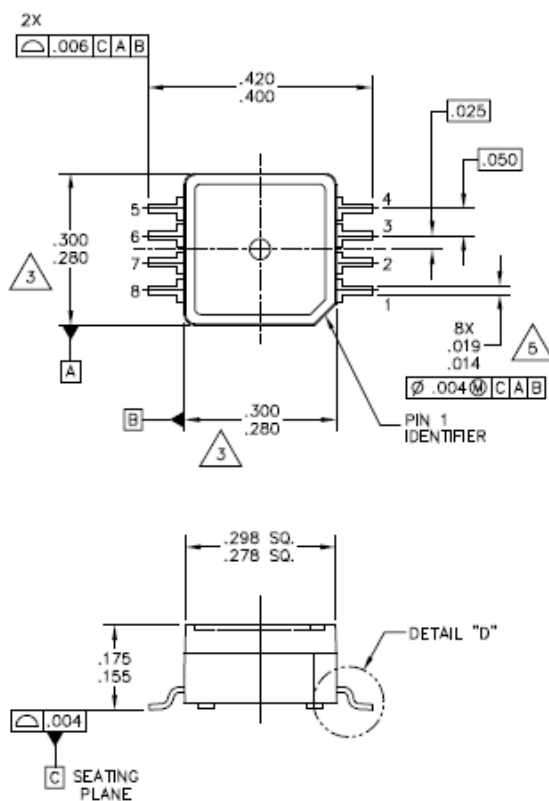
Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor package must be the correct size to ensure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self-align when subjected to a solder reflow process. It is always recommended to fabricate boards with a solder mask layer to avoid bridging and/or shorting between solder pads, especially on tight tolerances and/or tight layouts.

Figure 8. SSOP footprint



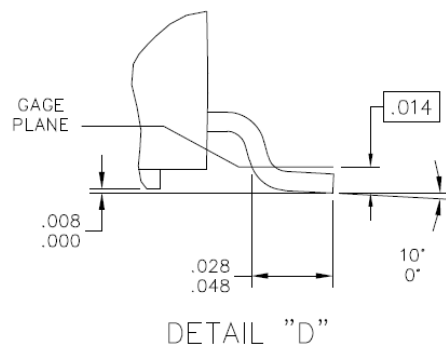
6 Package dimensions

Figure 9. Case 98ARH99066A, 8-lead super small outline package



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE: 8 LEAD SSOP		DOCUMENT NO: 98ARH99066A		REV: H	
		CASE NUMBER: 1317-04		13 APR 2012	
		STANDARD: NON-JEDEC			

Figure 10. Case 98ARH99066A, 8-lead super small outline package



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 8 LEAD SSOP		DOCUMENT NO: 98ARH99066A	REV: H
		CASE NUMBER: 1317-04	13 APR 2012
		STANDARD: NON-JEDEC	

Figure 11. Case 98ARH99066A, 8-lead super small outline package

NOTES:

1. ALL DIMENSIONS IN INCHES.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006 INCHES PER SIDE.
4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.
ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 INCHES MAXIMUM.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE: 8 LEAD SSOP	DOCUMENT NO: 98ARH99066A			REV: H	
	CASE NUMBER: 1317-04			13 APR 2012	
	STANDARD: NON-JEDEC				

Revision history

Table 5. Document revision history

Date	Revision	Changes
23-Jun-2026	1	Initial release from ST, rebranded NXP document

Contents

1	Ordering information	2
2	General description	3
2.1	Block diagram	3
2.2	Pinout	3
3	Mechanical and electrical specifications	4
3.1	Maximum ratings	4
3.2	Operating characteristics	4
4	On-chip temperature compensation and calibration	6
5	Package information	8
5.1	Minimum recommended footprint for super small packages	8
6	Package dimensions	9
	Revision history	12

IMPORTANT NOTICE – READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice.

In the event of any conflict between the provisions of this document and the provisions of any contractual arrangement in force between the purchasers and ST, the provisions of such contractual arrangement shall prevail.

The purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgment.

The purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of the purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

If the purchasers identify an ST product that meets their functional and performance requirements but that is not designated for the purchasers' market segment, the purchasers shall contact ST for more information.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2026 STMicroelectronics – All rights reserved